

/ Descriptions

SOT23-6

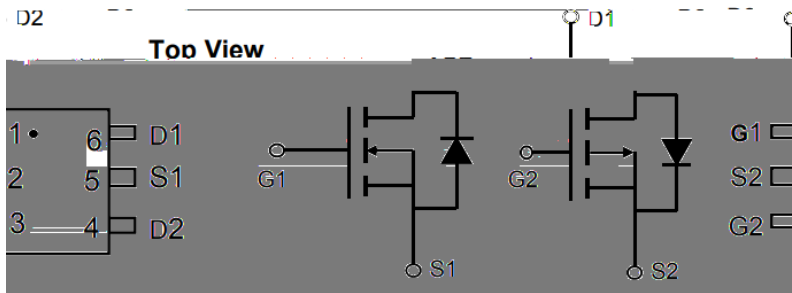
Complementary Enhancement MOSFET in a SOT23-6 Plastic Package.

/ Features

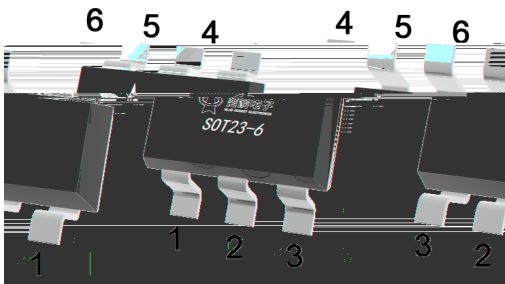
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/ Applications

/ Equivalent Circuit



/ Pinning



/ Marking

N- / N-CHANNEL Electrical Characteristic Curve

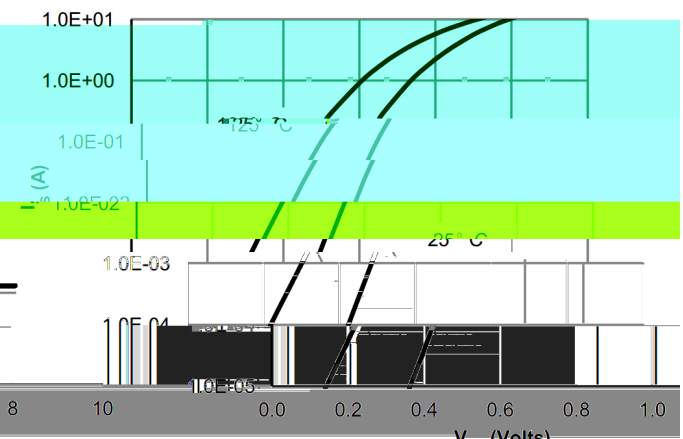
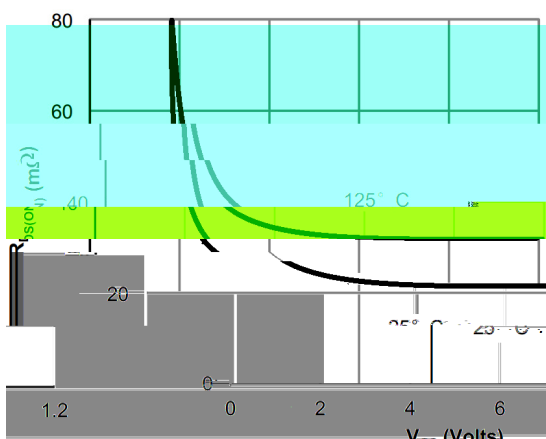
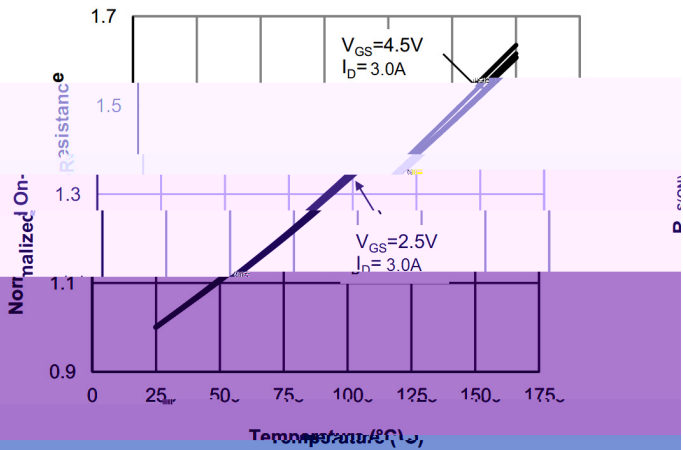
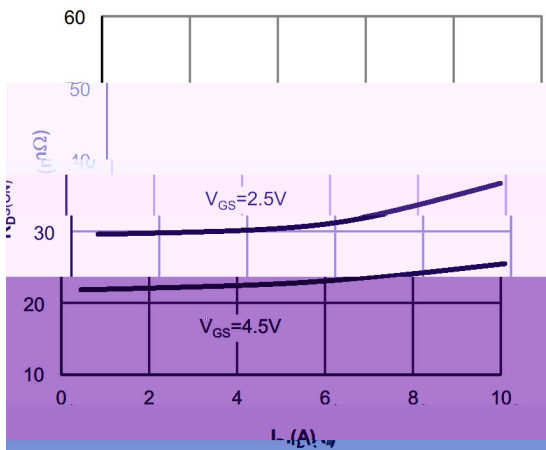
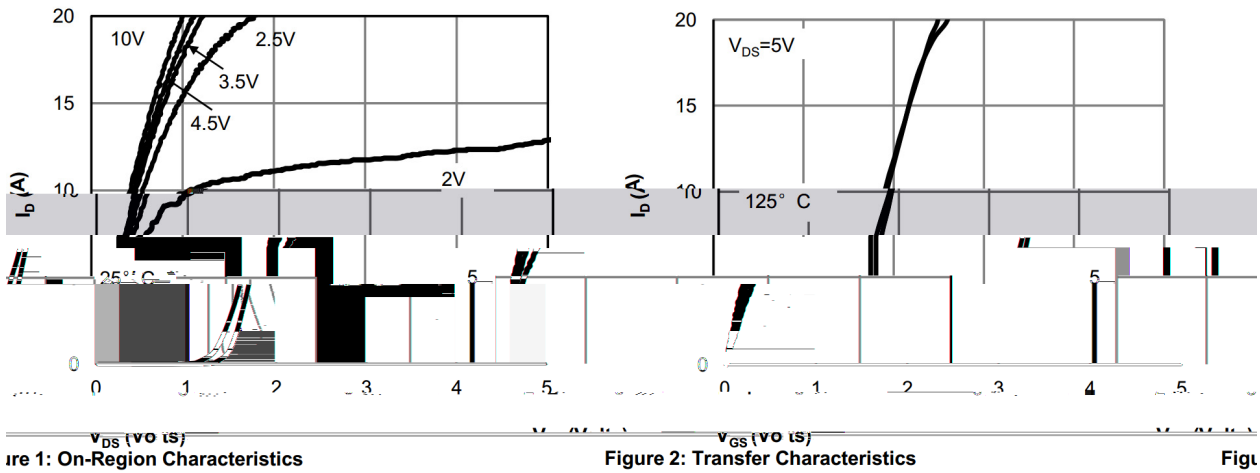


Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

N- / N-CHANNEL Electrical Characteristic Curve

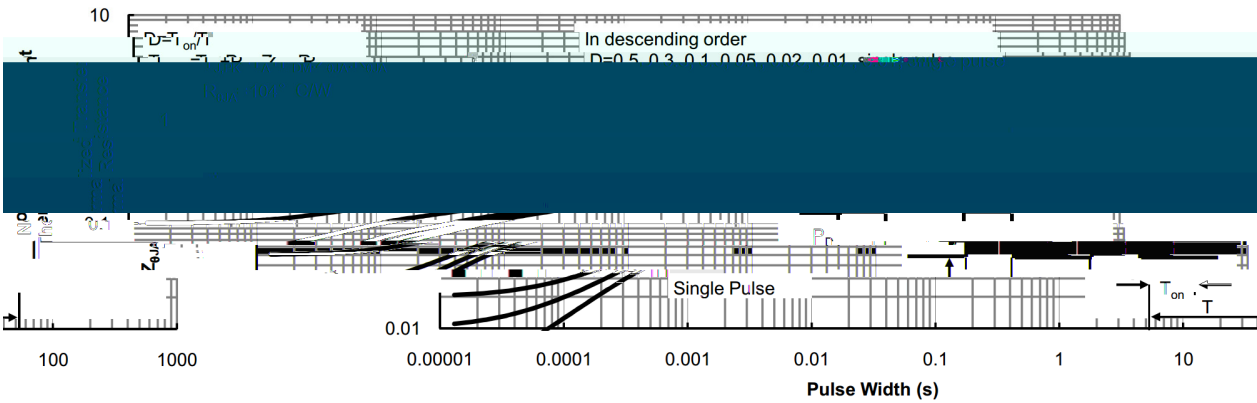
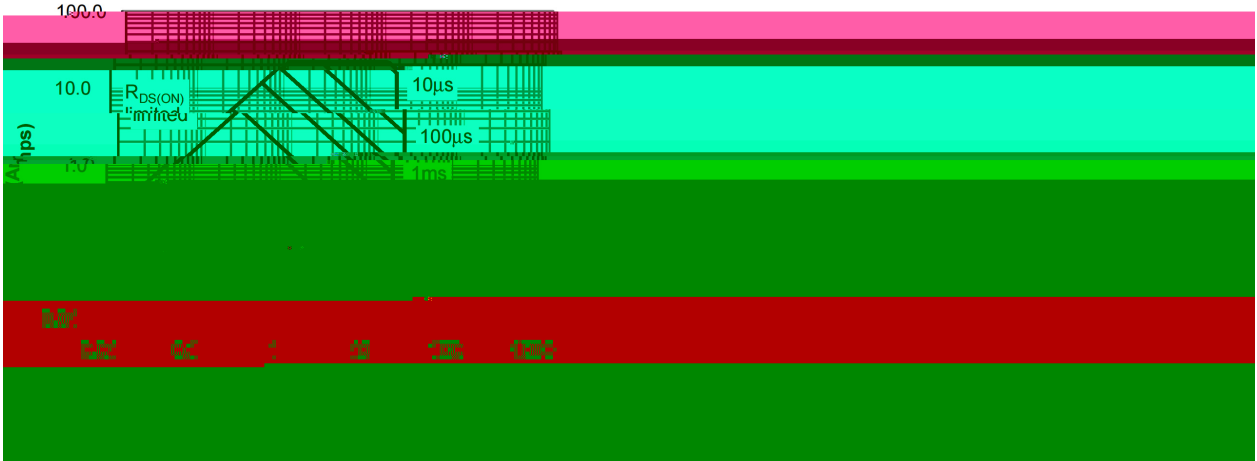
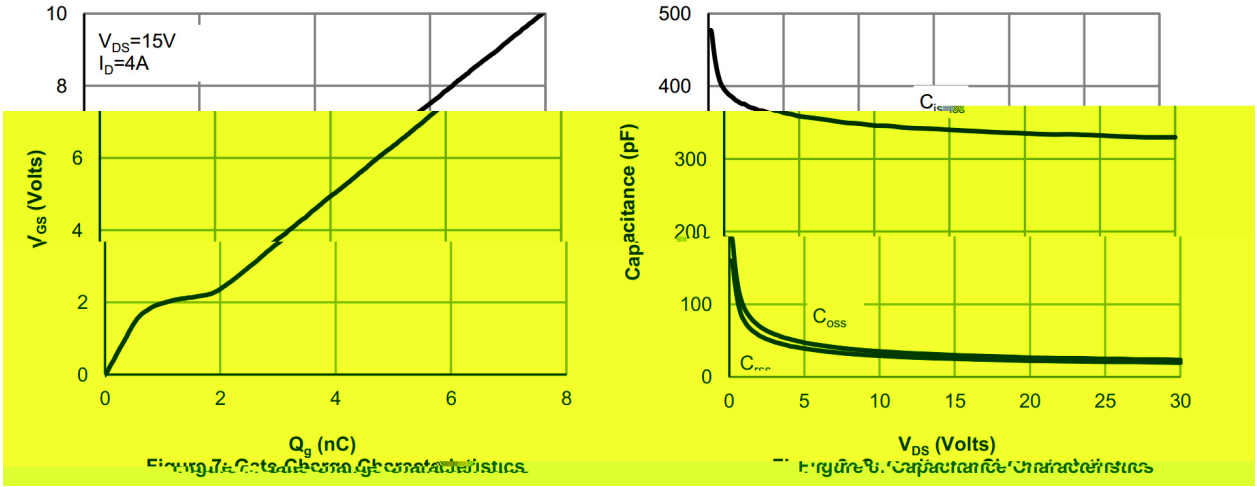


Figure 10: Normalized Maximum Transient Thermal Impedance

P- / P-CHANNEL Electrical Characteristic Curve

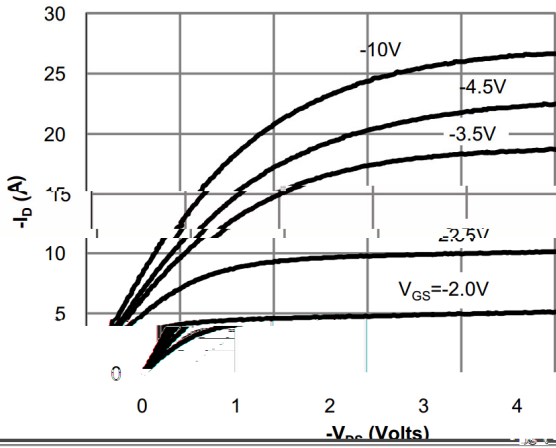


Fig 1: On-Region Characteristics

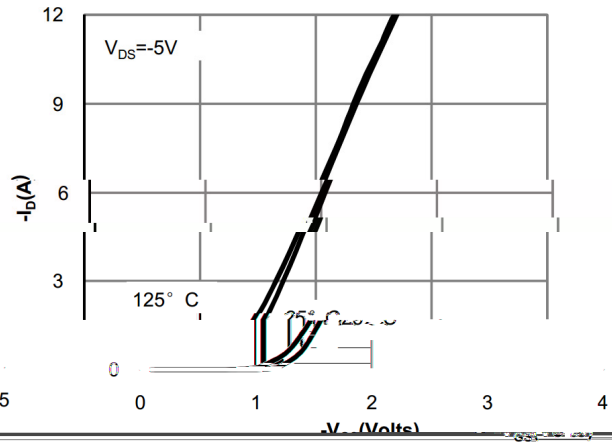


Figure 2: Transfer Characteristics

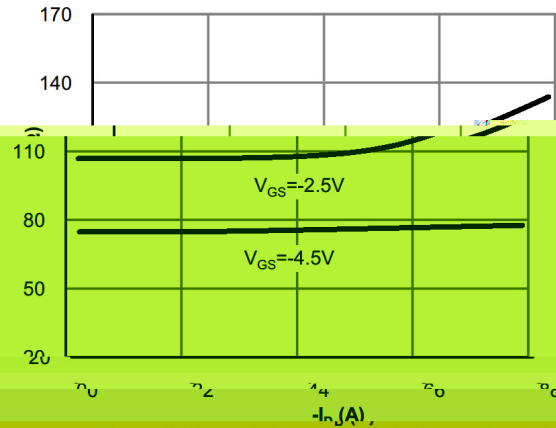


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

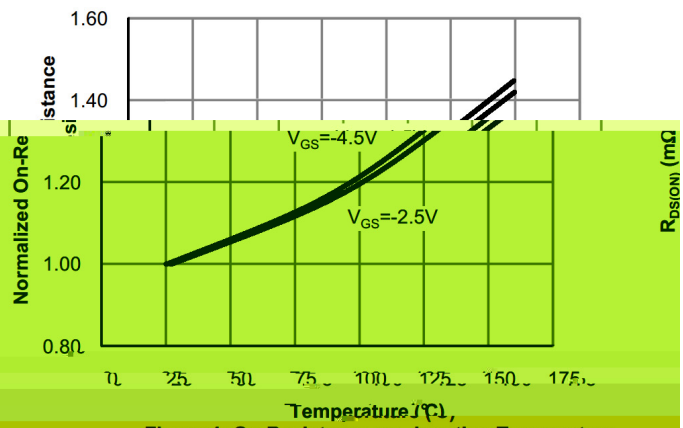
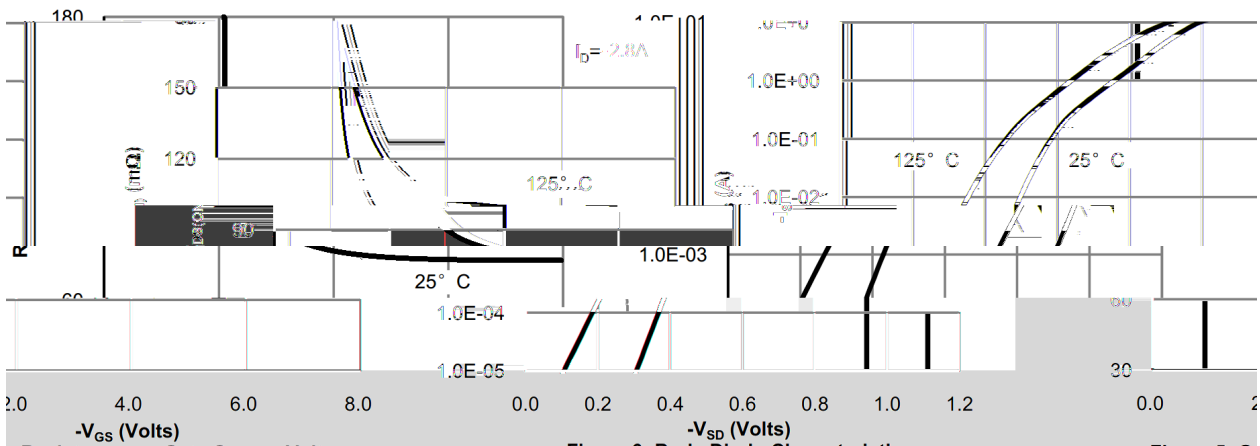


Figure 4: On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

Figure 5: On-Resistance vs. Junction Temperature

P- / P-CHANNEL Electrical Characteristic Curve

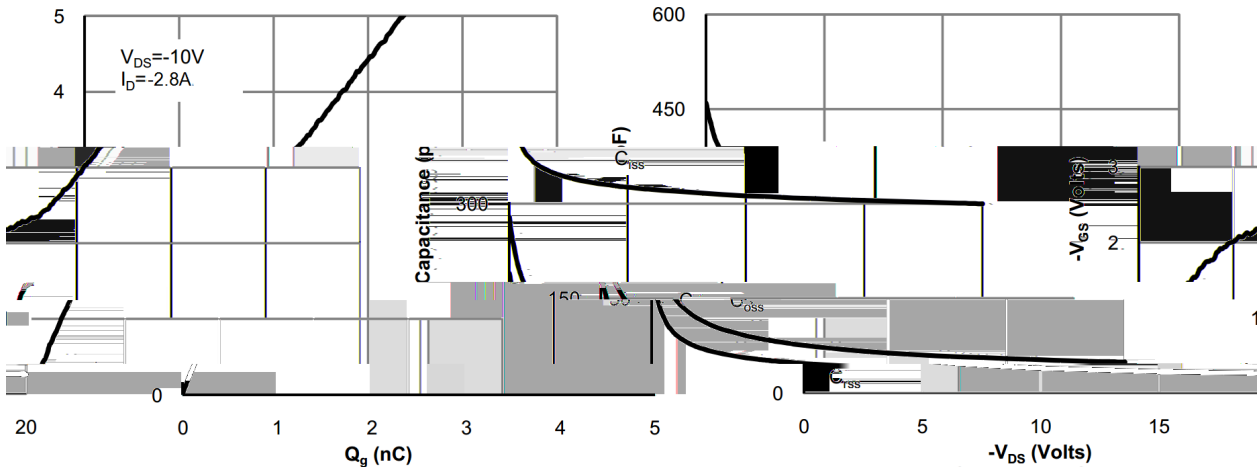


Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

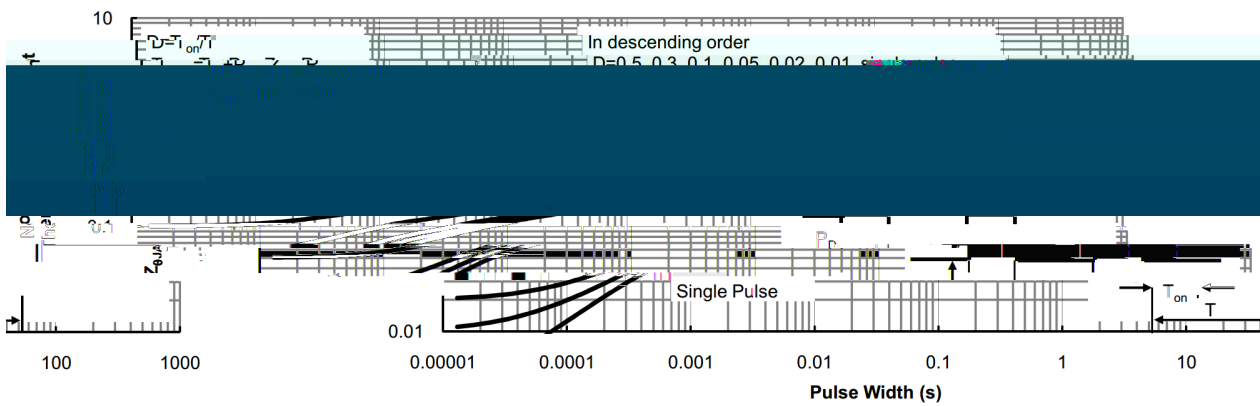
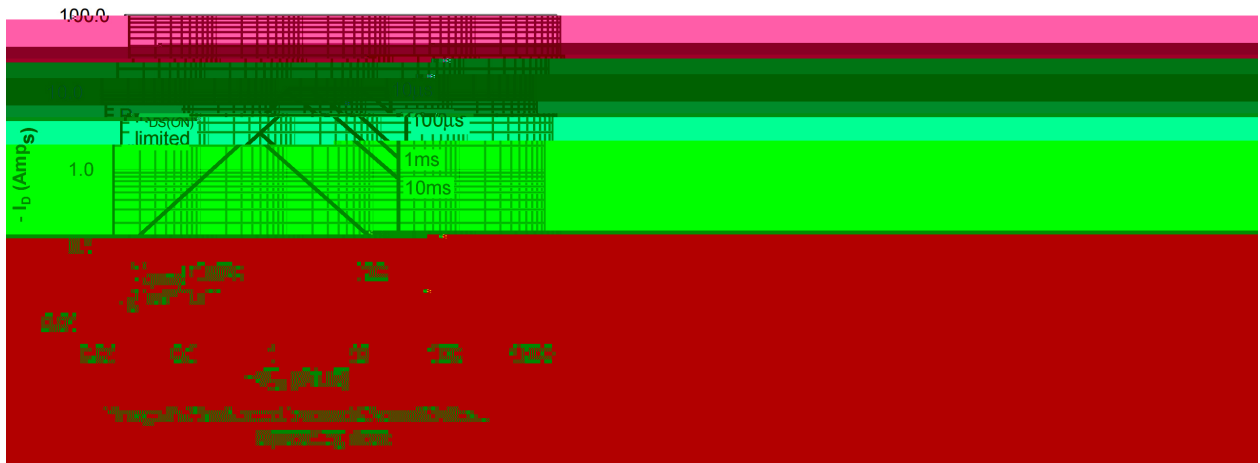
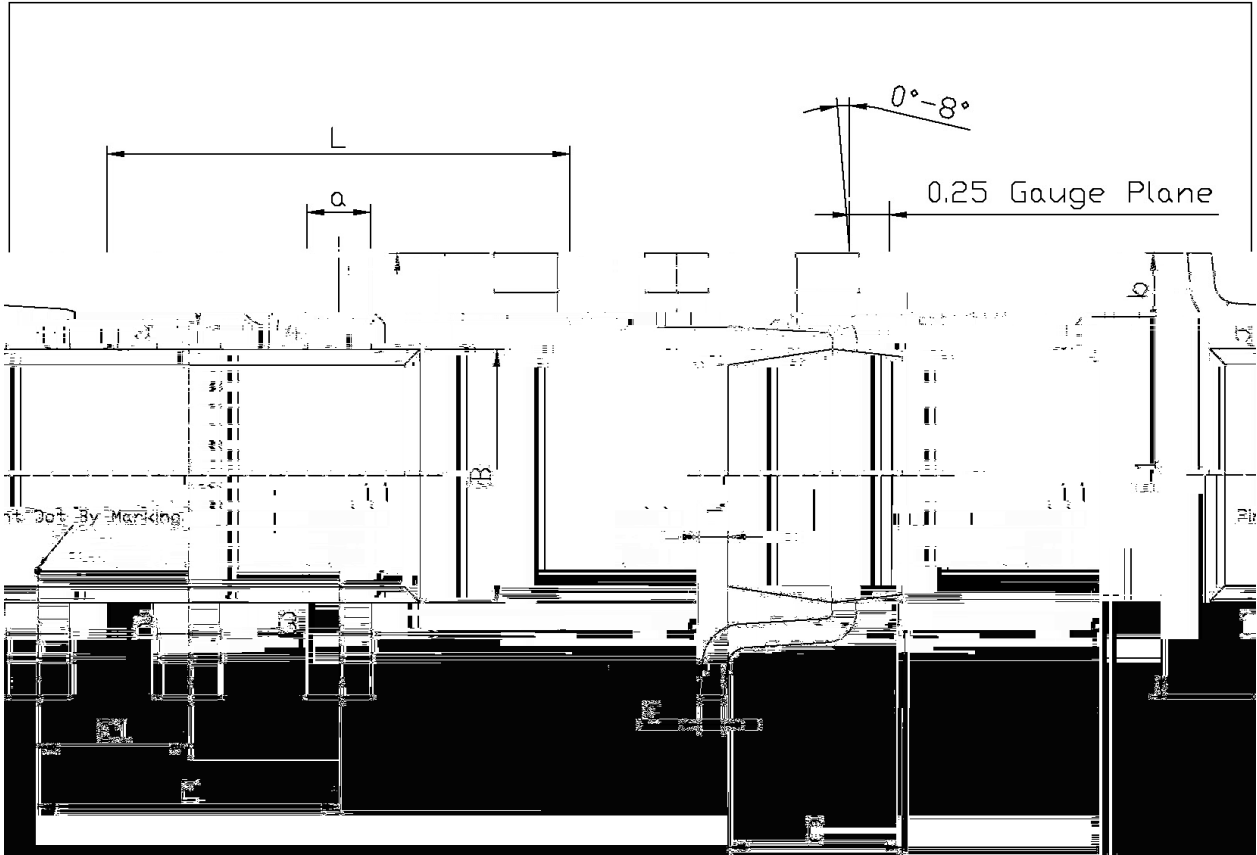


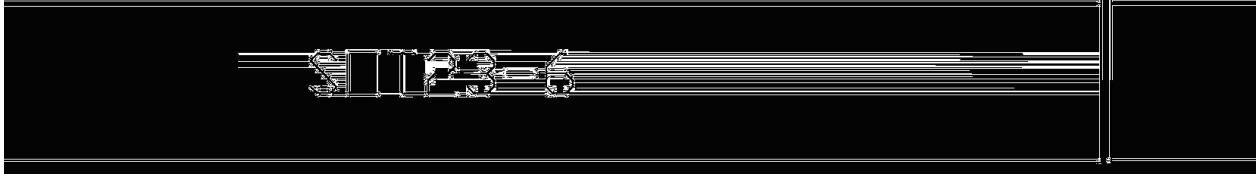
Figure 10: Normalized Maximum Transient Thermal Impedance

/ Package Dimensions

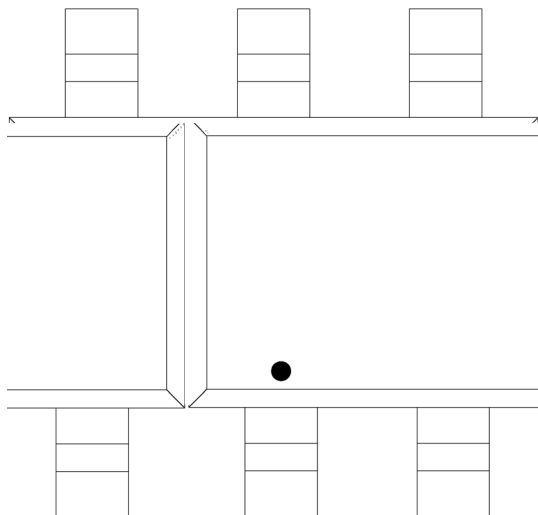


Unit: mm

Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
L	1.27	1.27	L1	0.25	0.25
a	0.51	0.51	a	0.25	0.25
B	0.51	0.51	B	0.25	0.25
B1	0.51	0.51	B1	0.25	0.25

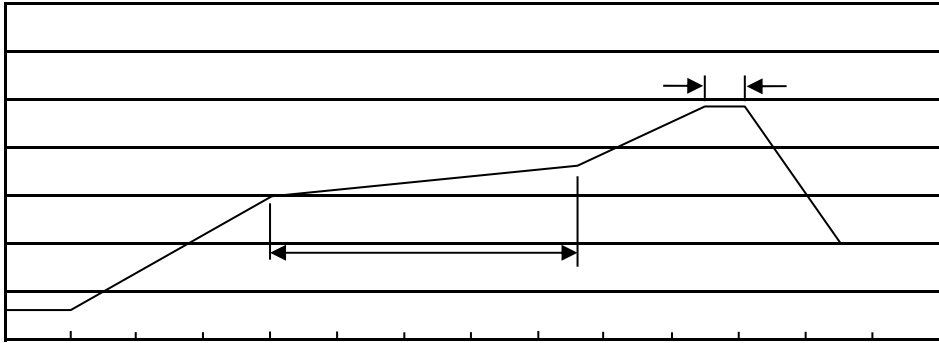


/ Marking Instructions



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() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box

/ Notices